

ULTRA-LOW IMPEDANCE POWER  
INTERCONNECTION SYSTEM FOR ELECTRONIC PACKAGES

ABSTRACT OF THE DISCLOSURE

5 A power interconnection system comprising a plurality of z-axis compliant connectors passing power and ground signals between a first circuit board to a second circuit board is disclosed. The interconnection system provides for an extremely low impedance through a broad range of frequencies and allows for large amounts of current to pass from one substrate to the next either statically or dynamically. The interconnection system may be  
10 located close to the die or may be further away depending upon the system requirements. The interconnection may also be used to take up mechanical tolerances between the two substrates while providing a low impedance. interconnect.

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DARLENE Ross

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Darlene Ross

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